

General Description

The WST2N7002B is the highest performance trench N-CH MOSFET with extreme high cell density , which provide excellent $R_{\rm DSON}$ and gate charge for most of the small power switching and load switch applications.

The WST2N7002B meet the RoHS and Green Product requirement with full function reliability approved.

Features

- High-speed switching
- Green Devide Available

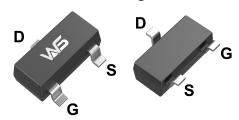
Product Summery

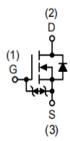
BV _{DSS}	R _{DSON}	I _D
60V	1800mΩ	0.3A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC
- Networking DC-DC Power System
- Load Switch

SOT-23L Pin Configuration





Absolute Maximum Ratings

Symbol	Parameter	Rating	Units	
V_{DS}	Drain-Source Voltage	60	V	
V_{GS}	Gate-Source Voltage	±20	V	
I _D @T _A =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	0.3	А	
I _D @T _A =70℃	Continuous Drain Current, V _{GS} @ 10V ¹	0.18	A	
I _{DM}	Pulsed Drain Current ²	1.2	А	
P _D @T _A =25°C	Total Power Dissipation ³	0.2	W	
T _{STG}	Storage Temperature Range	-55 to 150	C	
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}\mathbb{C}$	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{0JA}	Thermal Resistance Junction-Ambient ¹		625	°C/W



Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60			V	
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =1mA		0.05		V/°C	
-	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =0.3A		1800	1900	mΩ	
R _{DS(ON)}		V_{GS} =4.5V , I_D =0.2A		1900	2000		
V _{GS(th)}	Gate Threshold Voltage	\/ -\/ -250\	1	1.5	2.5	V	
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$-V_{GS}=V_{DS}$, $I_D=250uA$		-3.7		mV/℃	
	V _{DS} =60V , V _{GS} =0V , T _J =25℃				1		
I _{DSS}	Drain-Source Leakage Current	V_{DS} =60 V , V_{GS} =0 V , T_{J} =55 $^{\circ}$ C			5	uA	
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20 V$, V_{DS} = $0 V$			±10	uA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =0.3A		940		mS	
T _{d(on)}	Turn-On Delay Time			1.8	3.3		
Tr	Rise Time	ise Time V_{DD} =30V , V_{GS} =10V , R_{G} =3.3 Ω ,		3	6	200	
$T_{d(off)}$	Turn-Off Delay Time	I _D =0.5A		6.8	13.6	ns	
T _f	Fall Time			8	16	7	
C _{iss}	Input Capacitance			18	56		
C _{oss}	Output Capacitance V _{DS} =25V , V _{GS} =0V , f=1MHz			12	17	pF	
C _{rss}	Reverse Transfer Capacitance			7.6	10.6		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,4}	V =V =0V Force Current			0.18	Α
I _{SM}	Pulsed Source Current ^{2,4}	V _G =V _D =0V , Force Current			1.2	Α
V _{SD}	Diode Forward Voltage ²	V_{GS} =0V , I_{S} =1A , T_{J} =25 $^{\circ}$ C			1	V

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq~300 us$, duty cycle $\leq~2\%$
- 3. The power dissipation is limited by 150 ℃ junction temperature.
- 4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

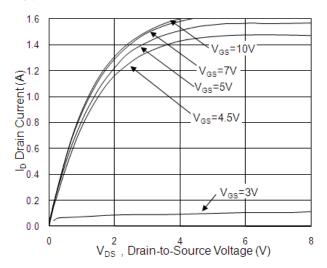


Fig.1 Typical Output Characteristics

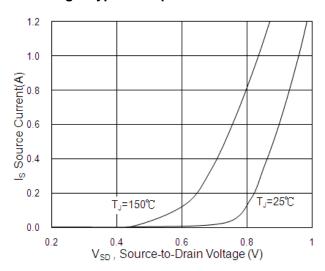


Fig.3 Forward Characteristics of Reverse

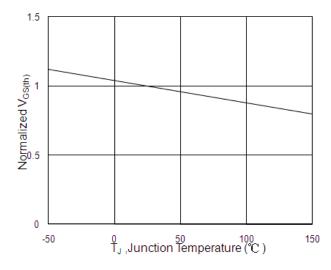


Fig.5 Normalized $V_{\text{GS(th)}}$ vs. T_{J}

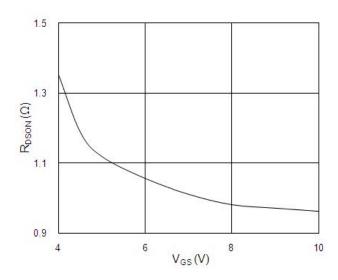


Fig.2 On-Resistance vs. Gate-Source Voltage

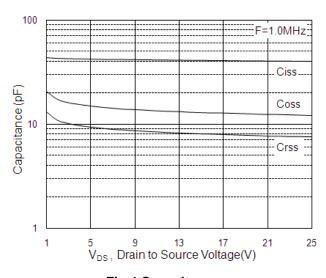


Fig.4 Capacitance

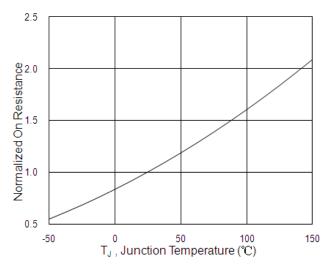
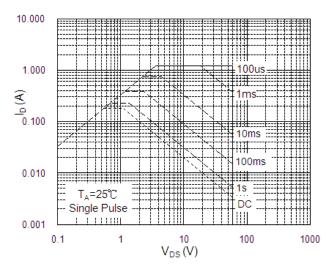


Fig.6 Normalized R_{DSON} vs. T_J





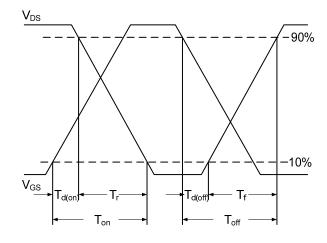


Fig.8 Safe Operating Area

Fig.10 Switching Time Waveform

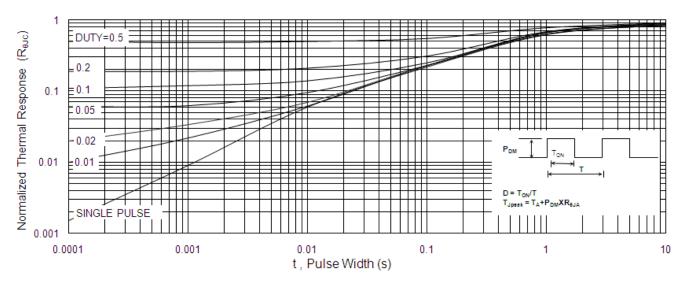
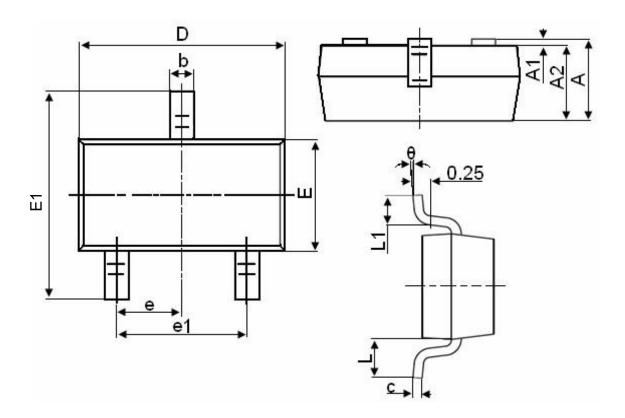


Fig.9 Normalized Maximum Transient Thermal Impedance



Packaging information



Cyrreb ol	Dimensions in Millimeters			
Symbol	MIN.	MAX.		
Α	0.900	1.150		
A1	0.000	0.100		
A2	0.900	1.050		
b	0.300	0.500		
С	0.080	0.150		
D	2.800	3.000		
Е	1.200	1.400		
E1	2.250	2.550		
е	0.99	0.950TYP		
e1	1.800	2.000		
L	0.550REF			
L1	0.300	0.500		
θ	0°	8°		



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